

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Hyen O. Oh</td><td>09/09/2008</td></tr><tr><td>In Hwan Choi</td><td>09/08/2008</td></tr><tr><td>Kook Yeon Kwak</td><td>09/09/2008</td></tr><tr><td>Byoung Gill Kim</td><td>09/08/2008</td></tr><tr><td>Won Gyu Song</td><td>09/08/2008</td></tr><tr><td>Jin Woo Kim</td><td>09/08/2008</td></tr><tr><td>Hyoung Gon Lee</td><td>09/08/2008</td></tr></tbody></table>		Name	Execution Date	Hyen O. Oh	09/09/2008	In Hwan Choi	09/08/2008	Kook Yeon Kwak	09/09/2008	Byoung Gill Kim	09/08/2008	Won Gyu Song	09/08/2008	Jin Woo Kim	09/08/2008	Hyoung Gon Lee	09/08/2008
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<table border="1"><tr><td>Name:</td><td>LG Electronics Inc.</td></tr><tr><td>Street Address:</td><td>20 YOIDO-DONG, YOUNGDUNGPO-GU</td></tr><tr><td>City:</td><td>Seoul</td></tr><tr><td>State/Country:</td><td>REPUBLIC OF KOREA</td></tr><tr><td>Postal Code:</td><td>150-010</td></tr></table>		Name:	LG Electronics Inc.	Street Address:	20 YOIDO-DONG, YOUNGDUNGPO-GU	City:	Seoul	State/Country:	REPUBLIC OF KOREA	Postal Code:	150-010						
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CORRESPONDENCE DATA																	
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PATENT
REEL: 027151 FRAME: 0133

ATTORNEY DOCKET NUMBER:	2080-3629C1
NAME OF SUBMITTER:	Puya Partow-Navid, Esq.
Total Attachments: 2 source=2080-3629C1-Assignment#page1.tif source=2080-3629C1-Assignment#page2.tif	

ASSIGNMENT

(1-8) *Insert Name(s) of
Inventor(s)*

(1) HYEN O OH	(5) WON GYU SONG
(2) IN HWAN CHOI	(6) JIN WOO KIM
(3) KOOK YEON KWAK	(7) HYOUNG GON LEE
(4) BYOUNG GILL KIM	(8)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(9) *Insert name of Assignee*

(9) **LG ELECTRONICS INC.**

(10) *Insert state of Incorporation
of Assignee*

(10) **Korea**

(11) *Insert address of Assignee*

(11) **20 Yoido-dong, Youngdungpo-gu,
Seoul, 150-010, Korea**

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

(12) *Insert identification of
Invention, such as Title,
Case Number or Foreign
Application Number*

(12) **BROADCASTING RECEIVER AND BROADCAST SIGNAL
PROCESSING METHOD (Application No. 12/167,234)**

for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

(13) *Insert Date of Signing of
Application*

(13)

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints the Attorneys associated with Customer No. 035884 the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: <u>Sep 9, 2008</u>	Signature of Inventor <u>[Signature]</u>
Date: <u>Sep 9, 2008</u>	Signature of Inventor <u>[Signature]</u>
Date: <u>Sep 9, 2008</u>	Signature of Inventor <u>[Signature]</u>
Date: <u>Sep 8, 2008</u>	Signature of Inventor <u>[Signature]</u>
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Date: _____	Signature of Inventor _____